

S2088BO-II

Economical AOI solution

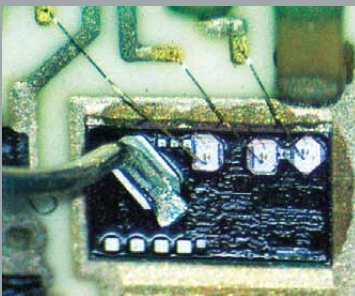
**Precise, reliable inspection
down to 17 μm wire diameters**

Wide inspection scope

**Very simple inspection
program generation**

**Completely compatible with
Viscom inline systems**

**Additional advantages as
programming station**



**Defect detection on bond
wires of different diameters**



**Defect detection on mul-
tiple wire connections
and multiple loops**



Reliable wirebond control with Desktop AOI

This compact AOI system was developed to inspect medium and small product runs. During inspection, a high-resolution camera records all bond sites and wires. Dies, bond sites, wire course and component position are only a part of the inspection scope. This system inspects everything from aluminum thick wire and aluminum or gold thin wire connections, down to diameters of 17 μm . Damage and misplaced components are also detected.

The Inspection system S2088BO-II is 100 % compatible with all Viscom inline systems and can also be employed as a programming station. Inspection programs are quickly and easily imported to in-line capable systems such as the S6053BO-V or S6056BO.

With the S2088BO-II, Viscom offers the performance capabilities of their high-end systems combined with the advantages of a compact, manually-operated desktop system.

AOI

Technical Specifications

S2088BO-II

Application

Ball-bond, wedge-bond, wire, die/SMD

Camera technology

Ultra-high resolution VHR module

Number of modules per machine	Typical 1
Number of mega pixel cameras	1
Pixel size	Typical 5 µm/pixel or 2.5 µm/pixel
	Further cameras available on request

Standard module 8M-1SRWBond

Number of modules per machine	Typical 1
Number of mega pixel cameras	1
Pixel size	Typical 11 µm/pixel
	Further cameras available on request

Software

User interface	Viscom EasyPro
Verification station	Viscom HARAN (integrated into system)
SPC	Viscom SPC (statistical process control), open interface (optional)
Remote diagnosis	Viscom SRC (software remote control) (optional)
Off-line programming	Viscom PST34 (external Programming Station) (optional)

System computer

Operating system	Windows®
Processor	PENTIUM® processing technology

PCB handling

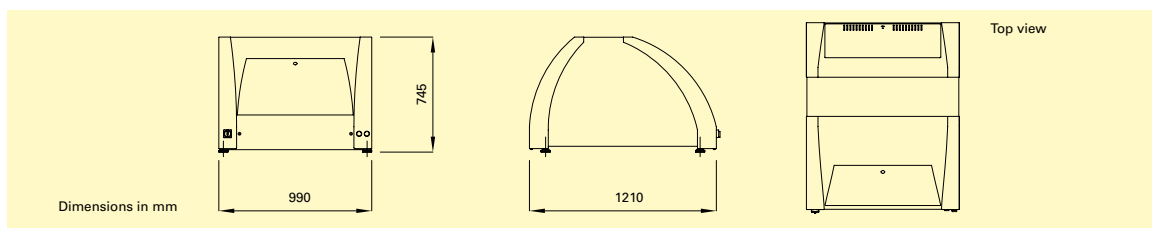
Substrate dimensions	8M-1SRWBond: 600 x 457 mm (23.6" x 18") (L x W) VHR module: 152 x 127 mm (5.9" x 5") (L x W), Other sizes on request
PCB thickness	1.0 - 6.0 mm (0.04" - 0.24")
Width adjustment	Manual
Handling unit	Synchronous linear motors
PCB clamping	Mechanical, upwards
PCB contact area	2.4 mm (0.09")
Upper transport clearance	9/15/35 mm (0.35"/0.59"/1.38") (depending on camera technology)
Lower transport clearance	60 mm (2.36")

Inspection speed

Up to 1000 wire bond connections/min.

Other system data

Power requirements	1 PN/PE, 110-240 V, 50/60 Hz, consumption < 1 kW
System dimensions	Approx. 990 x 1210 x 745 mm (39.0" x 47.6" x 29.3") (L x W x H)
Weight	Max. 130 kg (287 lbs)



Headquarters:

Viscom AG
Carl-Buderus-Str. 9 - 15 · 30455 Hanover · Germany
Tel.: +49 511 94996-0 · Fax: +49 511 94996-900
info@viscom.com · www.viscom.com

Visit our website to find international subsidiaries and representatives in Europe, USA and Asia:

www.viscom.com